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| | |
|-----------------|--|
| STRUCTURE | Silicon Monolithic Integrated Circuit |
| NAME OF PRODUCT | DC-AC Inverter Control IC |
| TYPE | BD9884FV |
| FUNCTION | <ul style="list-style-type: none"> · 2ch control with Half-bridge · Lamp current and voltage sense feed back control · Sequencing easily achieved with Soft Start Control · Short circuit protection with Timer Latch · Under Voltage Lock Out · Short circuit protection with over voltage · Mode-selectable the operating or stand-by mode by stand-by pin · 2ch BURST mode selectivity in-phase or reversed phase · Synchronous operating the other BD9884FV IC' s |

○Absolute Maximum Ratings (Ta = 25°C)

| Parameter | Symbol | Limits | Unit |
|------------------------------|--------|----------|------|
| Supply Voltage | Vcc | 12 | V |
| Operating Temperature Range | Topr | -35~+85 | °C |
| Storage Temperature Range | Tstg | -55~+125 | °C |
| Power Dissipation | Pd | 850* | mW |
| Maximum Junction Temperature | Tjmax | +125 | °C |

*Pd derated at 8.5mW/°C for temperature above Ta = 25°C (When mounted on a PCB 70.0mm×70.0mm×1.6mm)

○Recommended operating condition

| Parameter | Symbol | Limits | Unit |
|---------------------------|--------|-----------|------|
| Supply voltage | Vcc | 5.0~11.0 | V |
| CT oscillation frequency | fCT | 20~150 | kHz |
| BCT oscillation frequency | fBCT | 0.05~1.00 | kHz |

Status of this document

The Japanese version of this document is the official specification.

Please use the translation version of this document as a reference to expedite understanding of the official version.

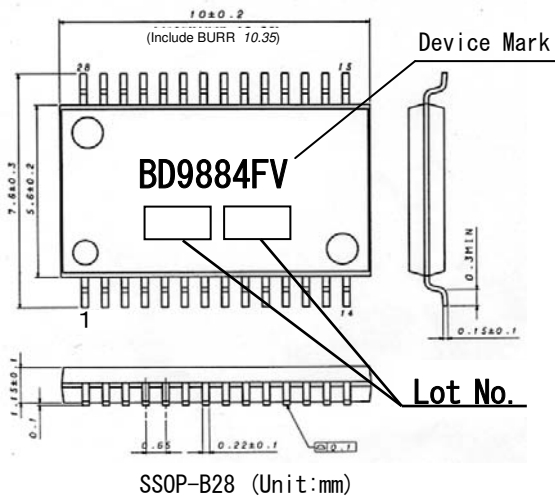
If there is any uncertainty in translation version of this document, official version takes priority.

○Electric Characteristics (Ta=25°C, VCC=7V)

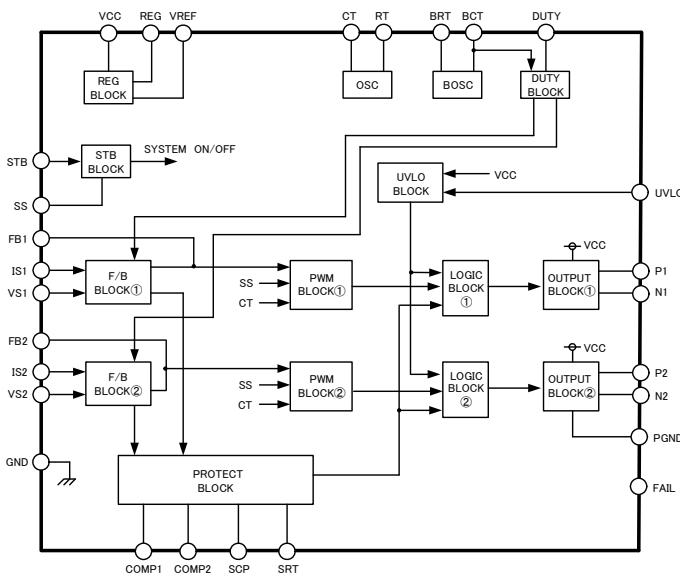
| Parameter | Symbol | Limits | | | Unit | Conditions |
|--|---------------------|----------|---------|----------|------|----------------------------|
| | | MIN. | TYP. | MAX. | | |
| ((WHOLE DEVICE)) | | | | | | |
| Operating current | Icc1 | — | 9.0 | 17.0 | mA | CT=0.5V |
| Stand-by current | Icc2 | — | 4 | 10 | μA | |
| ((OVER VOLTAGE DETECT)) | | | | | | |
| FB over voltage detect voltage | Vovf | 2.70 | 3.00 | 3.30 | V | |
| ((STAND BY CONTROL)) | | | | | | |
| Stand-by voltage H1 (BURST mode in reverse phase) | VstH1 | 2.4 | — | VCC | V | System ON |
| Stand-by voltage H2 (BURST mode in phase) | VstH2 | 1.4 | — | 1.8 | V | System ON |
| Stand-by voltage L | VstL | -0.3 | — | 0.5 | V | System OFF |
| Stand-by hysteresis | ΔVst | 0.10 | 0.25 | 0.40 | V | |
| ((TIMER LATCH)) | | | | | | |
| Timer Latch voltage | Vcp | 1.8 | 2.0 | 2.2 | V | |
| Timer Latch current | Icp | 0.5 | 1.0 | 1.5 | μA | |
| ((OSC BLOCK)) | | | | | | |
| OSC constant current | ICT | 1.35/RT | 1.5/RT | 1.65/RT | A | |
| OSC Max voltage | VoscH | 1.8 | 2.0 | 2.2 | V | fCT=60kHz |
| OSC Min voltage | VoscL | 0.3 | 0.5 | 0.7 | V | fCT=60kHz |
| MAX DUTY | MAXDUTY | 44 | 46.5 | 49 | % | fCT=60kHz |
| Soft start current | Iss | 1.0 | 2.0 | 3.0 | μA | |
| IS COMP detect Voltage | Visc | 0.45 | 0.60 | 0.75 | V | |
| SS COMP detect voltage | Vss | 2.0 | 2.2 | 2.4 | V | |
| SRT ON resistance | RSRT | — | 200 | 400 | Ω | |
| ((UVLO BLOCK)) | | | | | | |
| Operating voltage | VuvloH | 4.100 | 4.300 | 4.500 | V | |
| Lock out voltage | VuvloL | 3.900 | 4.100 | 4.300 | V | |
| Operating voltage (External UVLO) | Vuvlo1 | 1.900 | 2.000 | 2.100 | V | |
| Lock out voltage (External UVLO) | Vuvlo2 | 2.100 | 2.200 | 2.300 | V | |
| ((FEED BACK BLOCK)) | | | | | | |
| IS threshold voltage | Vis | 1.220 | 1.250 | 1.280 | V | |
| VS threshold voltage | Vvs | 1.220 | 1.250 | 1.280 | V | |
| IS source current 1 | Iis1 | — | — | 1.5 | μA | DUTY=2.0V |
| IS source current 2 | Iis2 | 13.0 | 20.0 | 27.0 | μA | DUTY=0V, IS=0.5V |
| VS source current | Ivs | — | — | 1.0 | μA | |
| ((OUTPUT BLOCK)) | | | | | | |
| Pch output voltage H | VoutPH | VCC-0.3 | VCC-0.1 | — | V | |
| Nch output voltage H | VoutNH | VCC-0.3 | VCC-0.1 | — | V | |
| Pch output voltage L | VoutPL | — | 0.1 | 0.3 | V | |
| Nch output voltage L | VoutNL | — | 0.1 | 0.3 | V | |
| Pch output sink resistance | RsinkP | — | 8 | 16 | Ω | I _{sink} = 10mA |
| Pch output source resistance | RsourceP | — | 10 | 20 | Ω | I _{source} = 10mA |
| Nch output sink resistance | RsinkN | — | 8 | 16 | Ω | I _{sink} = 10mA |
| Nch output source resistance | RsourceN | — | 10 | 20 | Ω | I _{source} = 10mA |
| ((BURST MODE BLOCK)) | | | | | | |
| BOSC Max voltage | VburH | 1.92 | 2.0 | 2.08 | V | fBCT=0.3kHz |
| BOSC Min Voltage | VburL | 0.4 | 0.5 | 0.6 | V | fBCT=0.3kHz |
| BOSC constant current | IBCT | 1.35/BRT | 1.5/BRT | 1.65/BRT | A | |
| ((REG BLOCK)) | | | | | | |
| REG output voltage | VREG | 3.038 | 3.100 | 3.162 | V | |
| REG source current | I _{REG} | 5.0 | — | — | mA | |
| VREF voltage | Vref | 1.220 | 1.250 | 1.280 | V | |
| ((COMP BLOCK)) | | | | | | |
| Over voltage detect | V _{COMP} H | 2.20 | 2.5 | 2.80 | V | |
| Under voltage detect | V _{COMP} L | 0.590 | 0.640 | 0.690 | V | |
| ((PROTECT CLOCK)) | | | | | | |
| Normal output voltage | VPH | 2.9 | 3.1 | 3.3 | V | |
| Protect output voltage | VPL | — | — | 0.5 | V | |

(This product is not designed for normal operation with in a radio active environment.)

○Package Dimensions



○Block Diagram



○Pin Description

| Pin No. | Pin Name | Function |
|---------|----------|--|
| 1 | DUTY | Control PWM mode and BURST mode |
| 2 | BRT | External resistor from BRT to GND for adjusting the BURST triangle oscillator |
| 3 | BCT | External capacitor from BCT to GND for adjusting the BURST triangle oscillator |
| 4 | RT | External resistor from SRT to RT for adjusting the triangle oscillator |
| 5 | SRT | External resistor from SRT to RT for adjusting the triangle oscillator |
| 6 | CT | External capacitor from CT to GND for adjusting the triangle oscillator |
| 7 | GND | GROUND |
| 8 | FB1 | Error amplifier output① |
| 9 | IS1 | Error amplifier input① |
| 10 | VS1 | Error amplifier input② |
| 11 | FB2 | Error amplifier output② |
| 12 | IS2 | Error amplifier input③ |
| 13 | VS2 | Error amplifier input④ |
| 14 | VREF | Reference voltage for ISNEGE, VSENCE error amplifier |
| 15 | FAIL | Protect clock output |
| 16 | STB | Stand-by switch |
| 17 | COMP1 | Under, over voltage detect for 1ch |
| 18 | COMP2 | Under, over voltage detect for 2ch |
| 19 | UVLO | External Under Voltage Lock OUT |
| 20 | REG | Internal regulator output |
| 21 | SS | External capacitor from SS to GND for Soft Start Control |
| 22 | SCP | External capacitor from SCP to GND for Timer Latch |
| 23 | P2 | FET driver for 2ch |
| 24 | N2 | FET driver for 2ch |
| 25 | PGND | Ground for FET drivers |
| 26 | N1 | FET driver for 1ch |
| 27 | P1 | FET driver for 1ch |
| 28 | VCC | Supply voltage input |

○NOTE FOR USE

1. When designing the external circuit, including adequate margins for variation between external devices and the IC. Use adequate margins for steady state and transient characteristics.
2. Recommended Operating Range
The circuit functionality is guaranteed within of ambient temperature operation range as long as it is within recommended operating range. The standard electrical characteristic values cannot be guaranteed at other voltages in the operating ranges, however, the variation will be small.
3. Mounting Failures
Mounting failures, such as misdirection or miscounts, may harm the device.
4. Electromagnetic Fields
A strong electromagnetic field may cause the IC to malfunction.
5. The GND pin should be the location within $\pm 0.3V$ compared with the PGND pin
6. BD9884FV has the short circuit protection with Thermal Shut Down System. When STB or Vcc pin re-supplied, They enables to cancel the latch. If It rise the temperature of the chip more than 170°C(TYP), It make the external FET OFF
7. Absolute maximum ratings are those values that, if exceeded, may cause the life of a device to become significantly shortened. Moreover, the exact failure mode caused by short or open is not defined. Physical countermeasures, such as a fuse, need to be considered when using a device beyond its maximum ratings.
8. About the external FET, the parasitic Capacitor may cause the gate voltage to change, when the drain voltage is switching. Make sure to leave adequate margin for this IC variation.
9. On operating Slow Start Control (SS is less than 2.2V), It does not operate Timer Latch.
10. By STB voltage, BD9884FV is changed to 3 states. Therefore, do not input STB pin voltage between one state and the other state (0.5~1.4V, 1.8~2.4V).
11. The pin connected a connector need to connect to the resistor for electrical surge destruction.
12. This IC is a monolithic IC which (as shown is Fig-1) has P⁺ substrate and between the various pins. A P-N junction is formed from this P layer of each pin. For example, the relation between each potential is as follows.
 - (When GND > PinB and GND > PinA, the P-N junction operates as a parasitic diode.)
 - (When PinB > GND > PinA, the P-N junction operates as a parasitic transistor.)
 Parasitic diodes can occur inevitably in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits as well as operation faults and physical damage. Accordingly you must not use methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND(P substrate)voltage to an input pin.

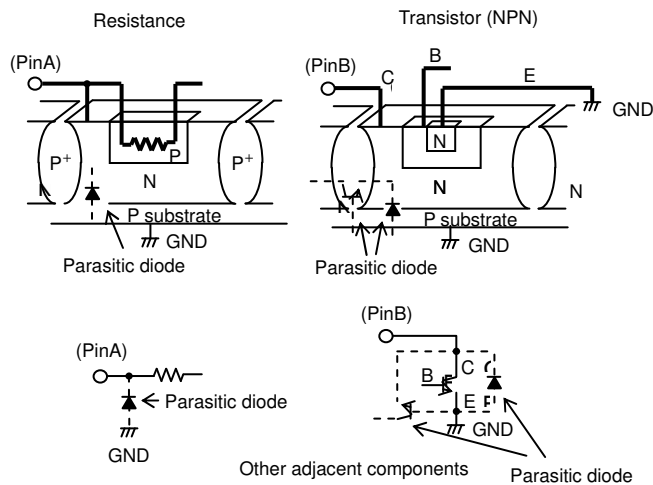


Fig-1 Simplified structure of a Bipolar IC

Notes

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